

Crystal OSCILLATOR

3.2 X2.5MM Surface Mount Package



Approved by:

Checked by:

Issued by:

SPECIFICATION

P/N: 3N1200000C01MBL

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FEATURE

- Compact and thin ceramic package with metalized surface mounting and automatically loaded
- Reflow solder is possible
- Lower noise and current with reduced power consumption
- Built-in C-MOS IC with tri-state function

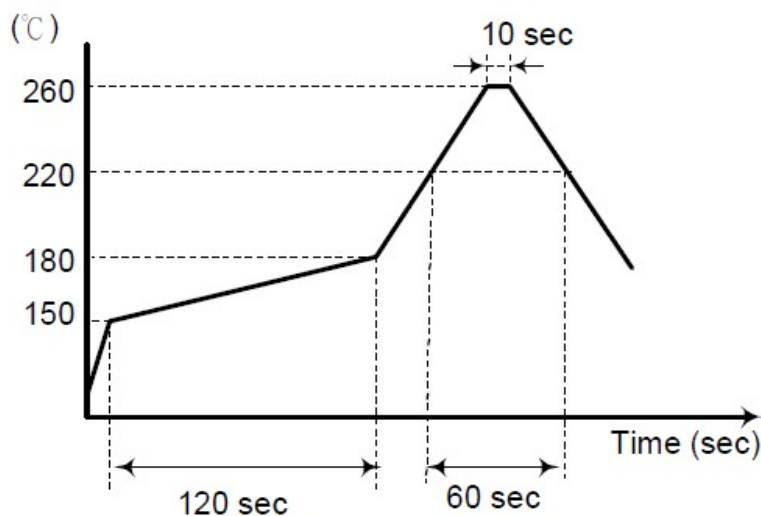
ELECTRICAL SPECIFICATIONS

Parameters	Condition\Model	
Fan Out Type		HCMOS
Supply Voltage		3.3V
Frequency		12.000MHz
Operating Temperature		-40°C ~ +85°C
Input Current	Frequency Range	10mA max
Frequency Stability	All Conditions	±50ppm
Symmetry	AT 1/2 Vdd	45/55%
Output Voltage	Vol(max)	10%Vdd
	VoH(min)	90%Vdd
Rise/Fall Time	AT 0.1Vdd~0.9Vdd	10ns Max
Driving Ability	CMOS load max	15pF
Start-up Time	Load RANGE	10ns max
E/D Function	#1 OPEN	PIN #3 ACTIVE
	#1 >=70%Vdd	PIN #3 ACTIVE
	#1 <=30%Vdd	PIN #3 HighZ
PAD Connection		PIN#1 E/D
		PIN#2 GND
		PIN#3 OUT
		PIN#4 Vdd

Reflow Soldering Profile

Total Time: 200 sec. Max.

Solder Melting Point :220 °C



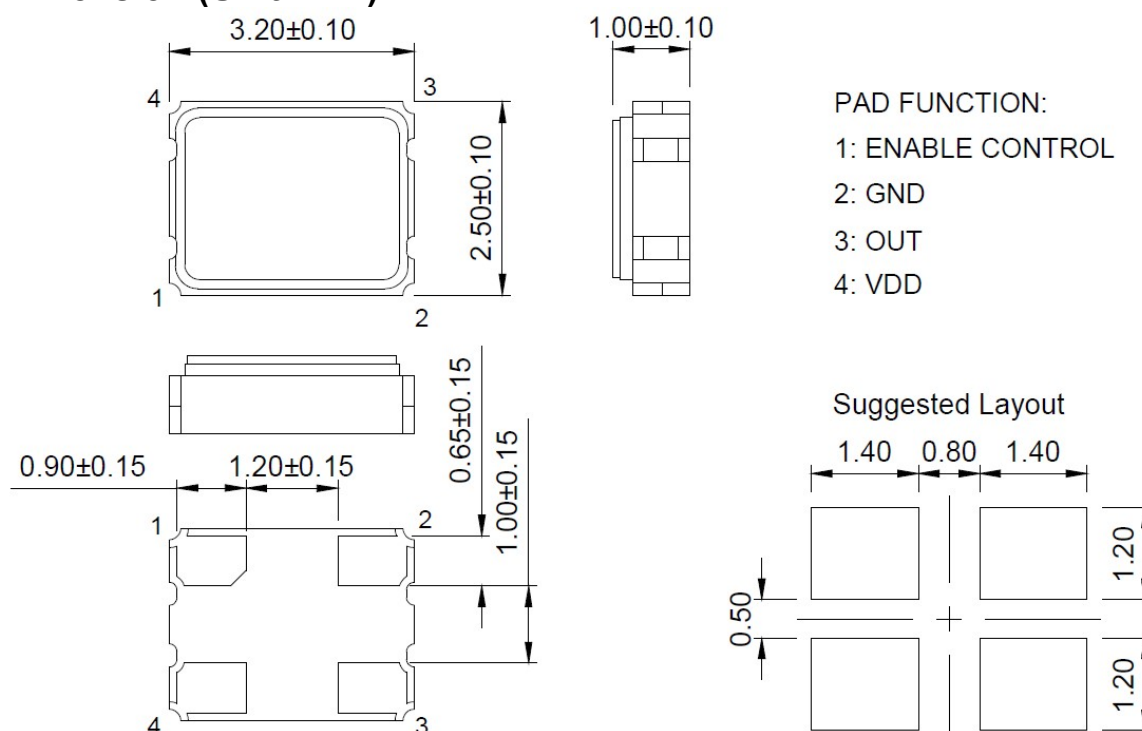
The design, manufacturing process, and specifications of this device are subject to change without notice.

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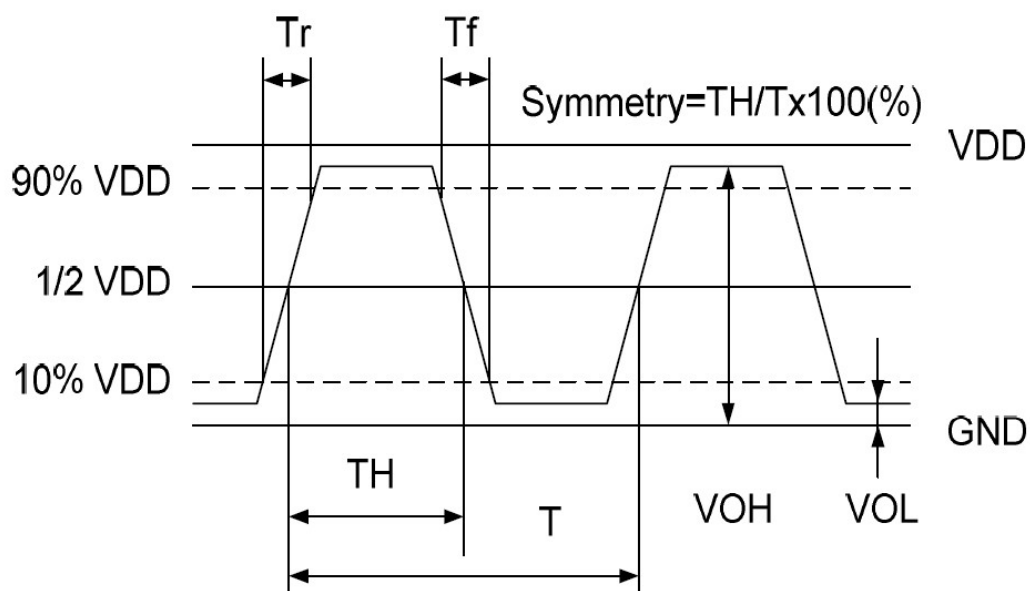
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Dimension (Unit: mm)



Waveform Conditions



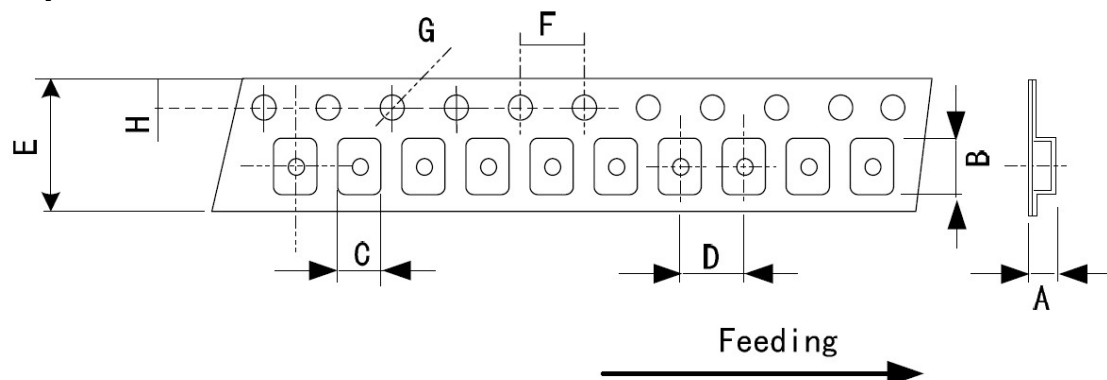
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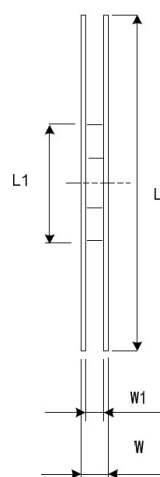
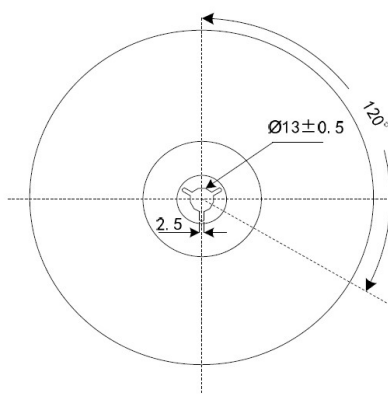
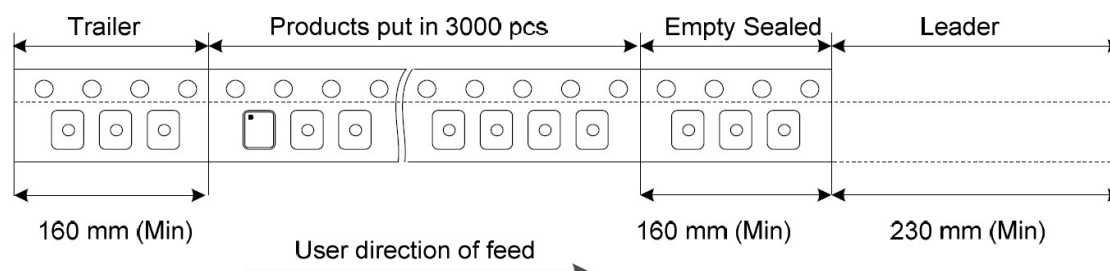


Tape Dimension



DIMENSIONS	A	B	C	D	E	F	G	H	(UNIT:mm)
	1.65 ±0.10	3.40 ±0.10	2.70 ±0.10	4.00 ±0.10	8.00 ±0.20	4.00 ±0.10	1.55 ±0.05	1.75 ±0.10	

REMARK :



DIMENSIONS	L	L1	W	W1	Standard Reel Quantity is 3,000 pcs per reel (UNIT:mm)
	178 ±1.00	60.2 ±0.50	11.5 ±0.2	8 +1/-0	

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